

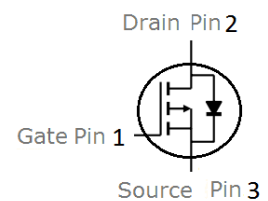
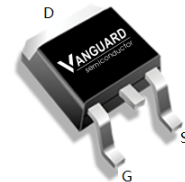
## Features

- P-Channel, -5V Logic Level Control
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=-4.5V$
- Fast Switching
- Enhancement mode
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant



Part ID	Package Type	Marking	Tape and reel information
VSD100P10MS	TO-252	100P10M	2500pcs/Reel

$V_{DS}$	-100	V
$R_{DS(on),TYP}@ V_{GS}=-10V$	92	m $\Omega$
$R_{DS(on),TYP}@ V_{GS}=-4.5V$	95	m $\Omega$
$I_D$	-17	A

**TO-252**


Maximum ratings, at  $T_j=25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit	
<b>Common Ratings</b>				
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-100	V	
$T_{STG} T_J$	Storage and operating temperature range <sup>①</sup>	-55 to 175	$^\circ\text{C}$	
$I_S$	Diode Continuous Forward Current	$T_C=25^\circ\text{C}$ -17	A	
<b>Mounted on Large Heat Sink</b>				
$I_D$	Continuous Drain current @ $V_{GS}=-10V$	$T_C=25^\circ\text{C}$	-17	A
		$T_C=100^\circ\text{C}$	-11	A
$I_{DM}$	Pulse Drain Current Tested <sup>②</sup>	$T_C=25^\circ\text{C}$	-50	A
$P_D$	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	57	W
$R_{\theta JC}$	Thermal Resistance-Junction to Case		2.6	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient		42	$^\circ\text{C/W}$
<b>Drain-Source Avalanche Ratings</b>				
EAS	Avalanche Energy, Single Pulsed <sup>③</sup>		210	mJ

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =-250μA	-100	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	--	--	-1	μA
	Zero Gate Voltage Drain Current(T <sub>j</sub> =125°C)	V <sub>DS</sub> =-100V, V <sub>GS</sub> =0V	--	--	-100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250μA	-1.0	-1.8	-2.5	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance ②	V <sub>GS</sub> =-10V, I <sub>D</sub> =-10A	--	92	105	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance ②	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-5A	--	95	115	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =-30V, V <sub>GS</sub> =0V, f=1MHz	--	2575	--	pF
C <sub>oss</sub>	Output Capacitance		--	90	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	75	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-50V, I <sub>D</sub> =-10A, V <sub>GS</sub> =-10V	--	37	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	8	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	9	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =-50V, I <sub>D</sub> =-10A, R <sub>G</sub> =6.8Ω, V <sub>GS</sub> =-10V	--	11	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	16	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	38	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	15	--	nS
<b>Source- Drain Diode Characteristics @ T<sub>j</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =-10A, V <sub>GS</sub> =0V	--	-0.87	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25°C, I <sub>sd</sub> =-20A, V <sub>GS</sub> =0V	--	25	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=-500A/μs		135		nC

**NOTE:**

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width ≤ 300μs; duty cycle ≤ 2%.
- ③ Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = -29A, V<sub>GS</sub> = -10V. Part not recommended for use above this value

Typical Characteristics

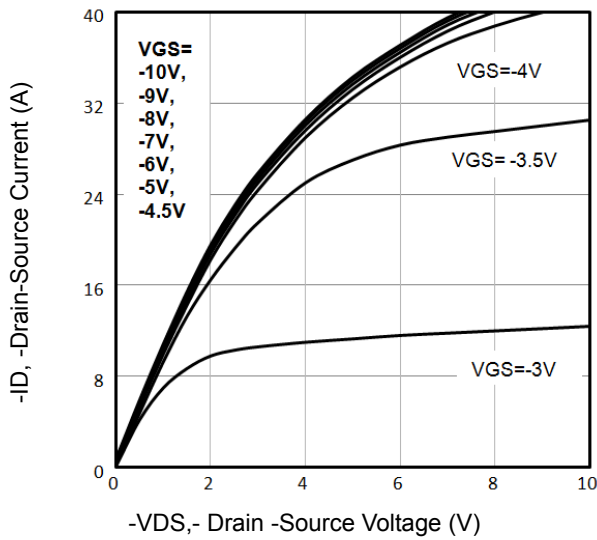


Fig1. Typical Output Characteristics

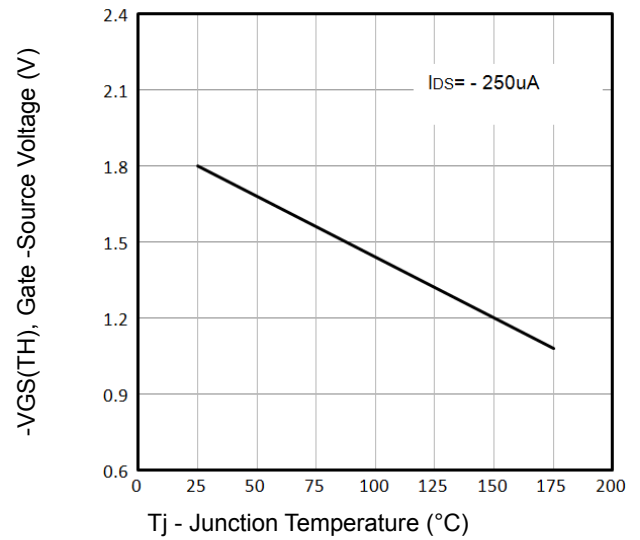


Fig2.  $-V_{GS(TH)}$  Gate -Source Voltage Vs.  $T_j$

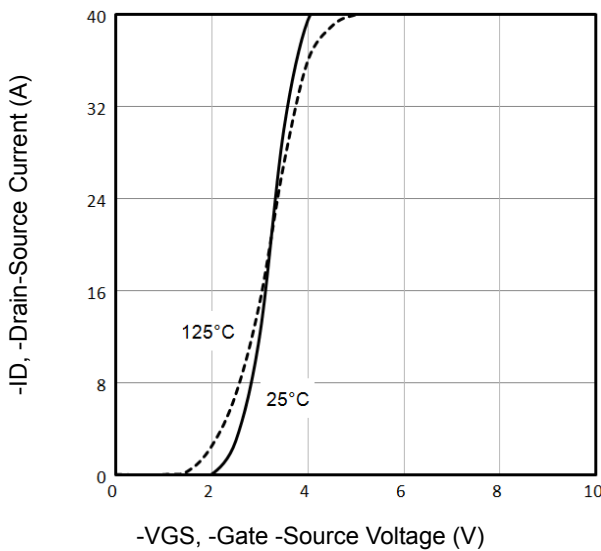


Fig3. Typical Transfer Characteristics

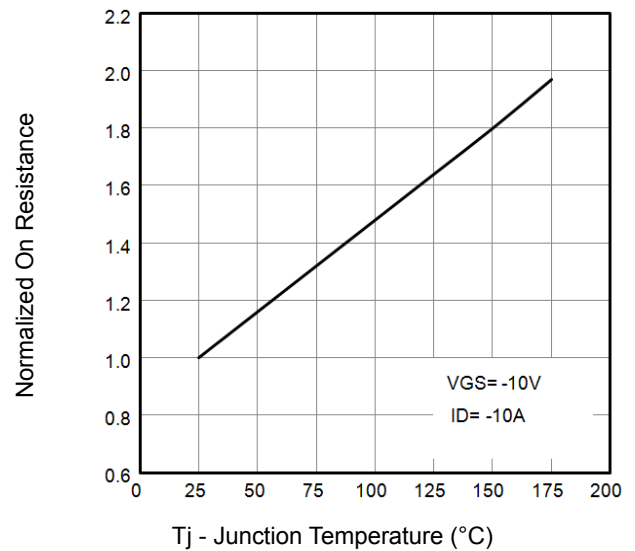


Fig4. Normalized On-Resistance Vs.  $T_j$

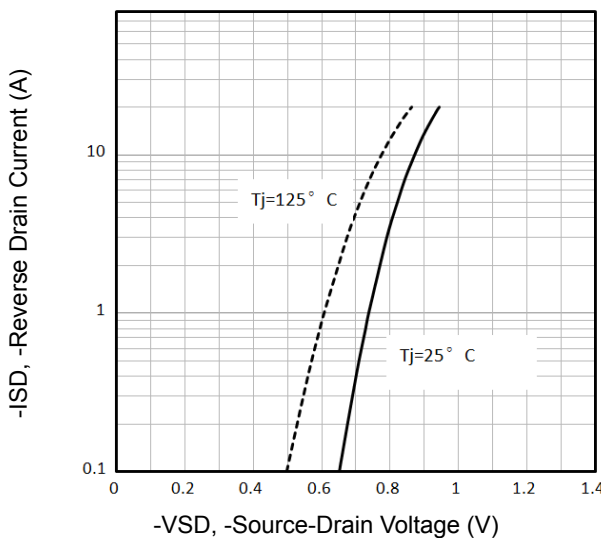


Fig5. Typical Source-Drain Diode Forward Voltage

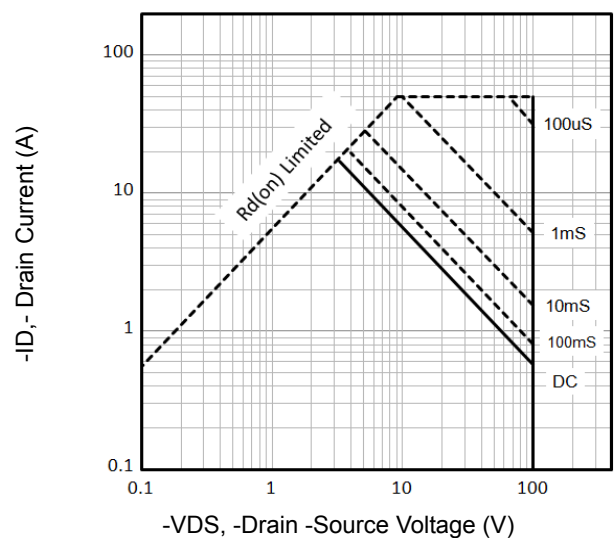


Fig6. Maximum Safe Operating Area

Typical Characteristics

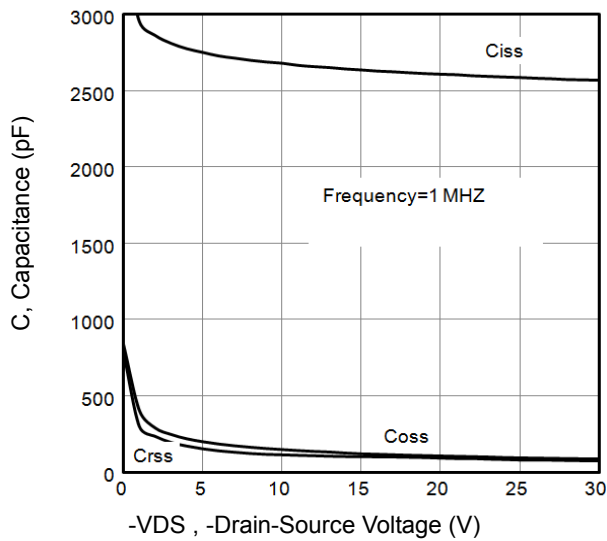


Fig7. Typical Capacitance Vs.Drain-Source Voltage

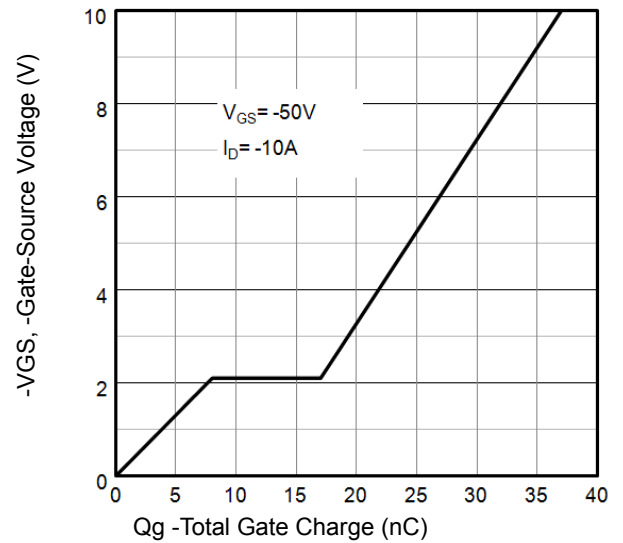


Fig8. Typical Gate Charge Vs.Gate-Source Voltage

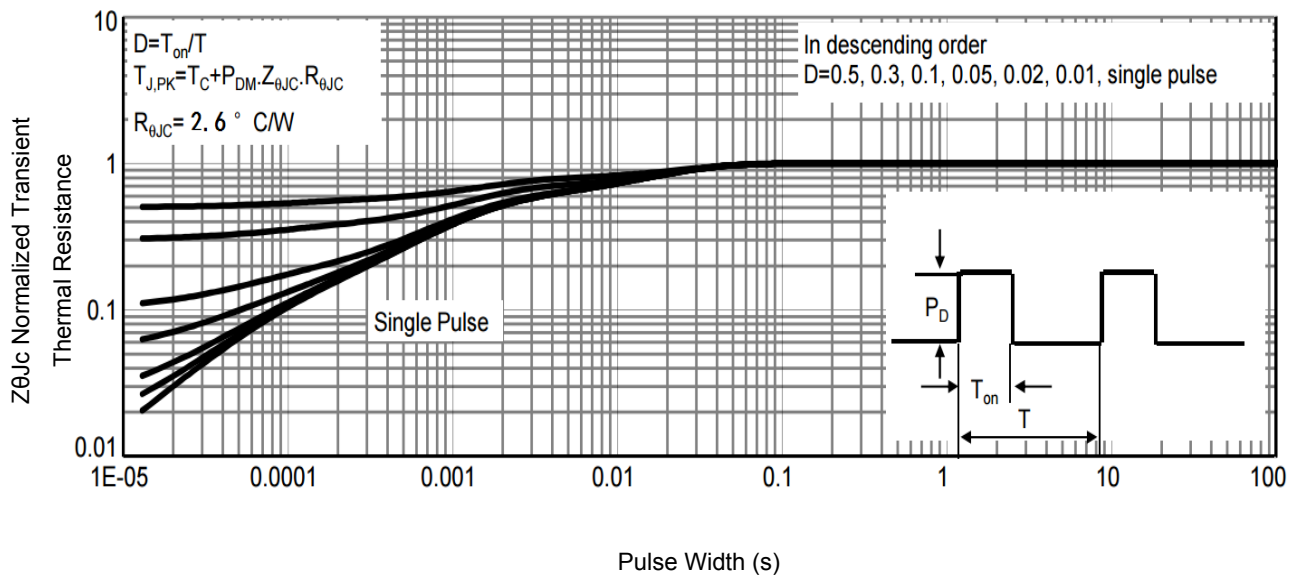


Fig9. Normalized Maximum Transient Thermal Impedance

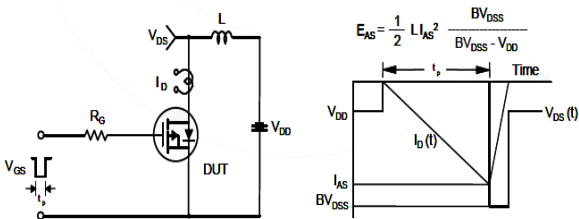


Fig10. Unclamped Inductive Test Circuit and Waveforms

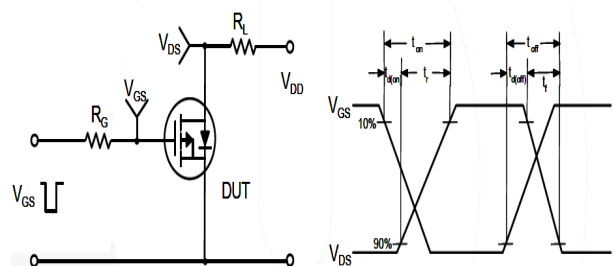
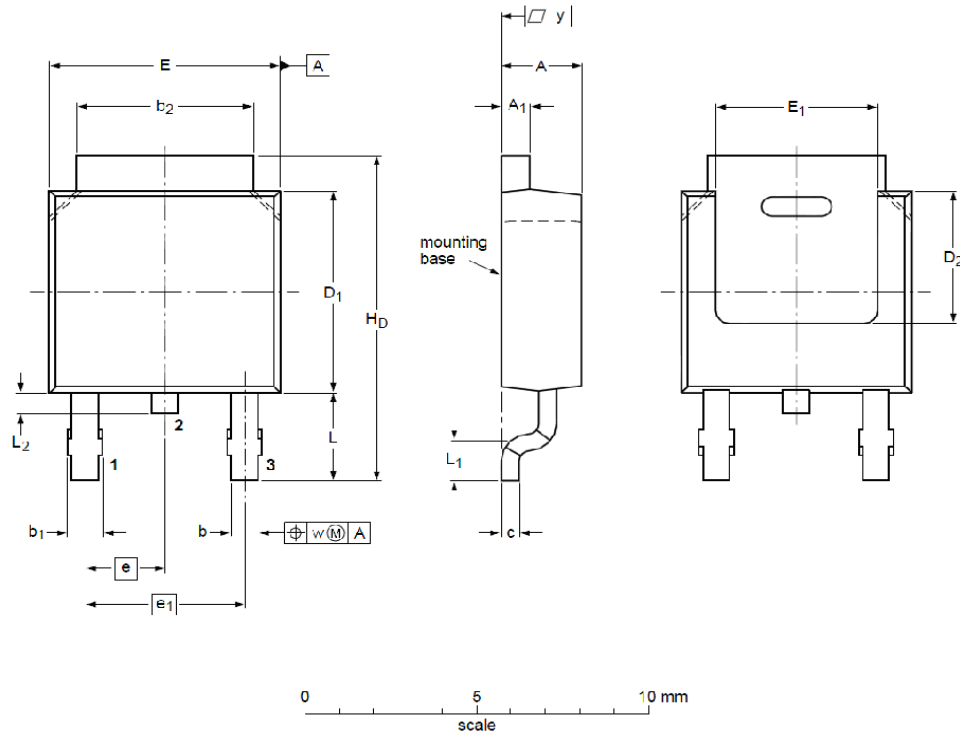


Fig11. Switching Time Test Circuit and waveforms

## TO-252 Package Outline Data



DIMENSIONS ( unit : mm )

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	2.22	2.30	2.38	A <sub>1</sub>	0.46	0.58	0.93
b	0.71	0.79	0.89	b <sub>1</sub>	0.90	0.98	1.10
b <sub>2</sub>	5.00	5.30	5.46	c	0.20	0.40	0.56
D <sub>1</sub>	5.98	6.05	6.22	D <sub>2</sub>	--	4.00	--
E	6.47	6.60	6.73	E <sub>1</sub>	5.10	5.28	5.45
e	--	2.28	--	e <sub>1</sub>	--	4.57	--
H <sub>D</sub>	9.60	10.08	10.40	L	2.75	2.95	3.05
L <sub>1</sub>	--	0.50	--	L <sub>2</sub>	0.80	0.90	1.10
w	--	0.20	--	y	0.20	--	--

## Customer Service

Sales and Service:

[sales@vgsemi.com](mailto:sales@vgsemi.com)

Vanguard Semiconductor CO., LTD

TEL: (86-755) -26902410

FAX: (86-755) -26907027

WEB: [www.vgsemi.com](http://www.vgsemi.com)